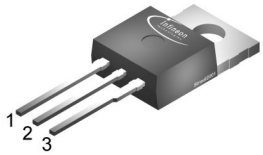
# BUZ 73L H

**SIPMOS ® Power Transistor**

- N channel
- Enhancement mode
- Avalanche-rated
- Logic Level
- Pb-free lead plating; RoHS compliant
. Halogen-free according to IEC61249-2-21




| Pin 1 | Pin 2 | Pin 3 |
|---|---|---|
| G | D | S |

| Type | $V_{DS}$ | $I_D$ | $R_{DS(on)}$ | Package | Pb-free |
|---|---|---|---|---|---|
| BUZ 73 L H | 200 V | 7 A | 0.4 Ω | PG-TO220-3 | Yes |

**Maximum Ratings**

| Parameter | Symbol | Values | Unit |
|---|---|---|---|
| Continuous drain current<br>$T_C$ = 28 °C | $I_D$ | 7 | A |
| Pulsed drain current<br>$T_C$ = 25 °C | $I_{Dpuls}$ | 28 | |
| Avalanche current,limited by $T_{jmax}$ | $I_{AR}$ | 7 | |
| Avalanche energy,periodic limited by $T_{jmax}$ | $E_{AR}$ | 6.5 | mJ |
| Avalanche energy, single pulse<br>$I_D$ = 7 A, $V_{DD}$ = 50 V, $R_{GS}$ = 25 Ω<br>$L$ = 3.67 mH, $T_j$ = 25 °C | $E_{AS}$ | 120 | |
| Gate source voltage | $V_{GS}$ | ± 20 | V |
| ESD-Sensitivity HBM as per MIL-STD 883 | | Class 1 | |
| Power dissipation<br>$T_C$ = 25 °C | $P_{tot}$ | 40 | W |
| Operating temperature | $T_j$ | -55 ... + 150 | °C |
| Storage temperature | $T_{stg}$ | -55 ... + 150 | |
| Thermal resistance, chip case | $R_{thJC}$ | ≤ 3.1 | K/W |
| Thermal resistance, chip to ambient | $R_{thJA}$ | 75 | |
| DIN humidity category, DIN 40 040 | | E | |
| IEC climatic category, DIN IEC 68-1 | | 55 / 150 / 56 | |

**Electrical Characteristics,** at $T_j$ = 25˚C, unless otherwise specified

| Parameter | Symbol | Values | | | Unit |
|---|---|---|---|---|---|
| | | min. | typ. | max. | |
| **Static Characteristics** | | | | | |
| Drain- source breakdown voltage<br>$V_{GS}$ = 0 V, $I_D$ = 0.25 mA, $T_j$ = 25 ˚C | $V_{(BR)DSS}$ | 200 | - | - | V |
| Gate threshold voltage<br>$V_{GS}$=$V_{DS}$, $I_D$ = 1 mA | $V_{GS(th)}$ | 1.2 | 1.6 | 2 | |
| Zero gate voltage drain current<br>$V_{DS}$ = 200 V, $V_{GS}$ = 0 V, $T_j$ = 25 ˚C<br>$V_{DS}$ = 200 V, $V_{GS}$ = 0 V, $T_j$ = 125 ˚C | $I_{DSS}$ | -<br>- | 0.1<br>10 | 1<br>100 | µA |
| Gate-source leakage current<br>$V_{GS}$ = 20 V, $V_{DS}$ = 0 V | $I_{GSS}$ | - | 10 | 100 | nA |
| Drain-Source on-resistance<br>$V_{GS}$ = 5 V, $I_D$ = 3.5 A | $R_{DS(on)}$ | - | 0.3 | 0.4 | Ω |

**Electrical Characteristics,** at $T_j$ = 25°C, unless otherwise specified

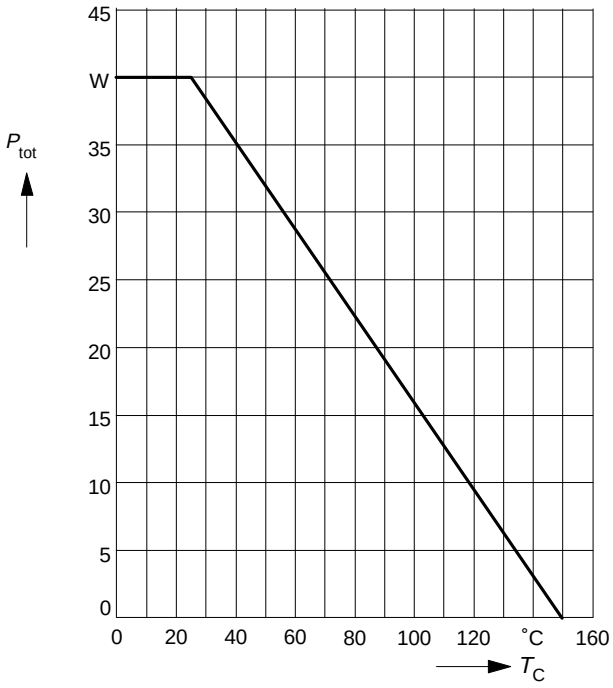
| Parameter | Symbol | Values | | | Unit |
|---|---|---|---|---|---|
| | | min. | typ. | max. | |
| **Dynamic Characteristics** | | | | | |
| Transconductance<br>$V_{DS} \geq 2 * I_D * R_{DS(on)max}$, $I_D$ = 3.5 A | $g_{fs}$ | 5 | 6.5 | - | S |
| Input capacitance<br>$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, $f$ = 1 MHz | $C_{iss}$ | - | 630 | 840 | pF |
| Output capacitance<br>$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, $f$ = 1 MHz | $C_{oss}$ | - | 120 | 200 | |
| Reverse transfer capacitance<br>$V_{GS}$ = 0 V, $V_{DS}$ = 25 V, $f$ = 1 MHz | $C_{rss}$ | - | 60 | 90 | |
| Turn-on delay time<br>$V_{DD}$ = 30 V, $V_{GS}$ = 5 V, $I_D$ = 3 A<br>$R_{GS}$ = 50 Ω | $t_{d(on)}$ | - | 15 | 20 | ns |
| Rise time<br>$V_{DD}$ = 30 V, $V_{GS}$ = 5 V, $I_D$ = 3 A<br>$R_{GS}$ = 50 Ω | $t_r$ | - | 60 | 90 | |
| Turn-off delay time<br>$V_{DD}$ = 30 V, $V_{GS}$ = 5 V, $I_D$ = 3 A<br>$R_{GS}$ = 50 Ω | $t_{d(off)}$ | - | 100 | 130 | |
| Fall time<br>$V_{DD}$ = 30 V, $V_{GS}$ = 5 V, $I_D$ = 3 A<br>$R_{GS}$ = 50 Ω | $t_f$ | - | 40 | 50 | |

**Electrical Characteristics,** at $T_j$ = 25˚C, unless otherwise specified

| Parameter | Symbol | Values | | | Unit |
|---|---|---|---|---|---|
| | | min. | typ. | max. | |
| **Reverse Diode** | | | | | |
| Inverse diode continuous forward current<br>$T_C$ = 25 ˚C | $I_S$ | - | - | 7 | A |
| Inverse diode direct current,pulsed<br>$T_C$ = 25 ˚C | $I_{SM}$ | - | - | 28 | |
| Inverse diode forward voltage<br>$V_{GS}$ = 0 V, $I_F$ = 14 A | $V_{SD}$ | - | 1.1 | 1.7 | V |
| Reverse recovery time<br>$V_R$ = 100 V, $I_F$=$I_S$, d$i_F$/d$t$ = 100 A/µs | $t_{rr}$ | - | 140 | - | ns |
| Reverse recovery charge<br>$V_R$ = 100 V, $I_F$=$I_S$, d$i_F$/d$t$ = 100 A/µs | $Q_{rr}$ | - | 0.7 | - | µC |

**Power dissipation**

$P_{tot} = f(T_C)$




**Drain current**

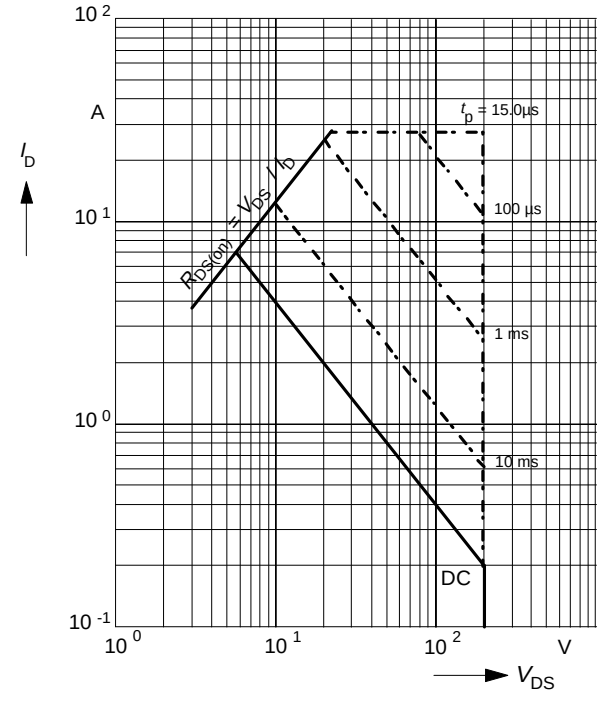
$I_D = f(T_C)$

parameter: $V_{GS} \geq 5$ V


**Safe operating area**

$I_D = f(V_{DS})$

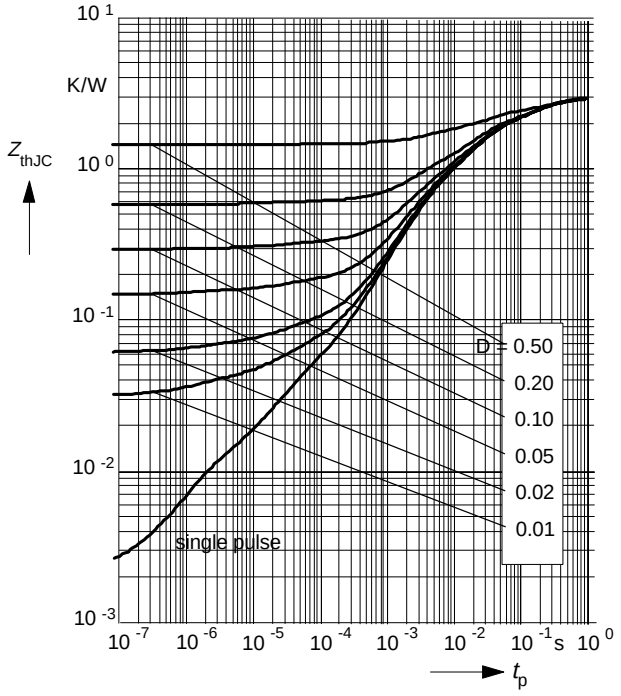
parameter: $D = 0.01$, $T_C = 25$°C




**Transient thermal impedance**

$Z_{th\,JC} = f(t_p)$

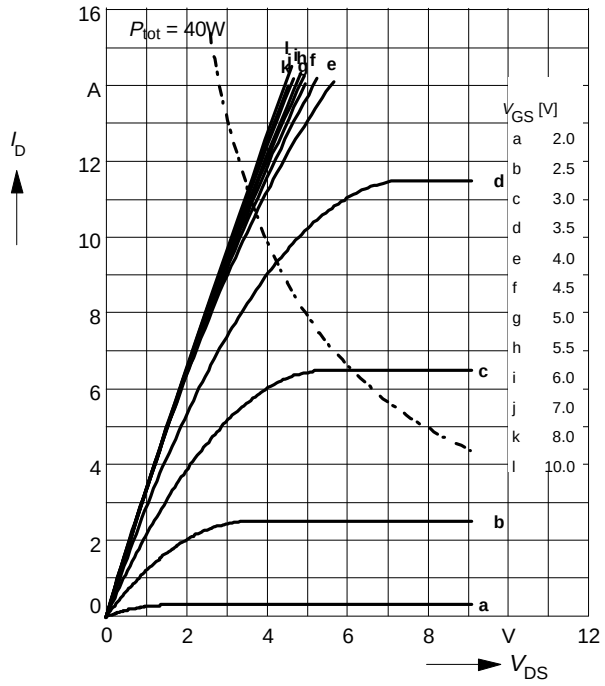
parameter: $D = t_p / T$



**Typ. output characteristics**

$I_D = f(V_{DS})$

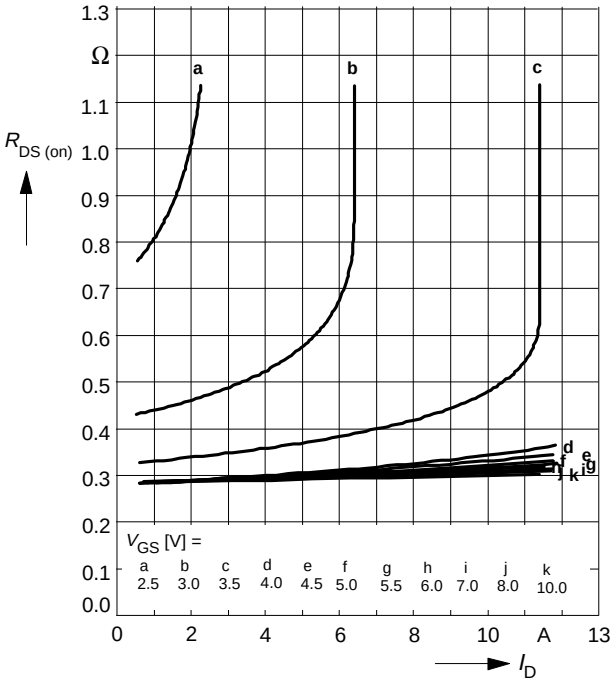
parameter: $t_p$ = 80 µs




**Typ. drain-source on-resistance**

$R_{DS\ (on)} = f(I_D)$

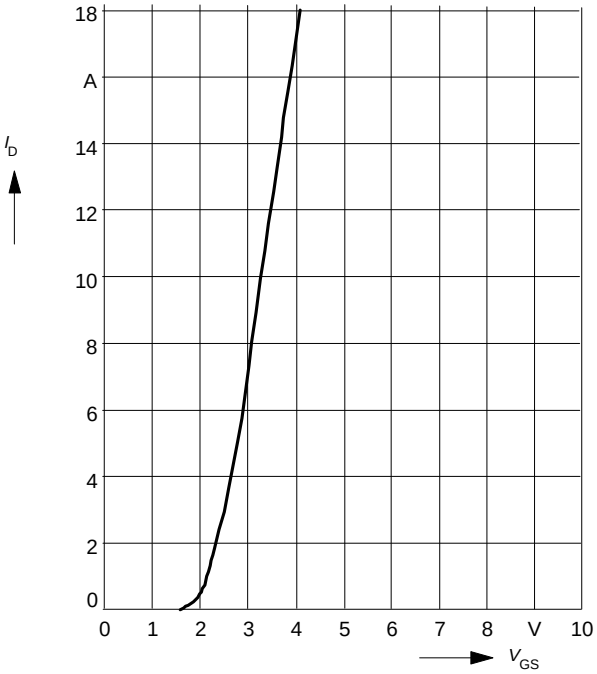
parameter: $V_{GS}$




**Typ. transfer characteristics** $I_D = f(V_{GS})$

parameter: $t_p$ = 80 µs

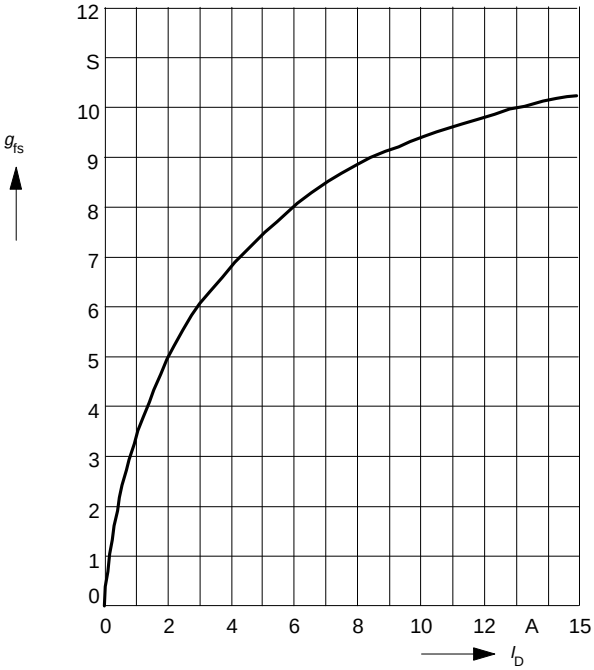
$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$




**Typ. forward transconductance** $g_{fs} = f(I_D)$

parameter: $t_p$ = 80 µs,

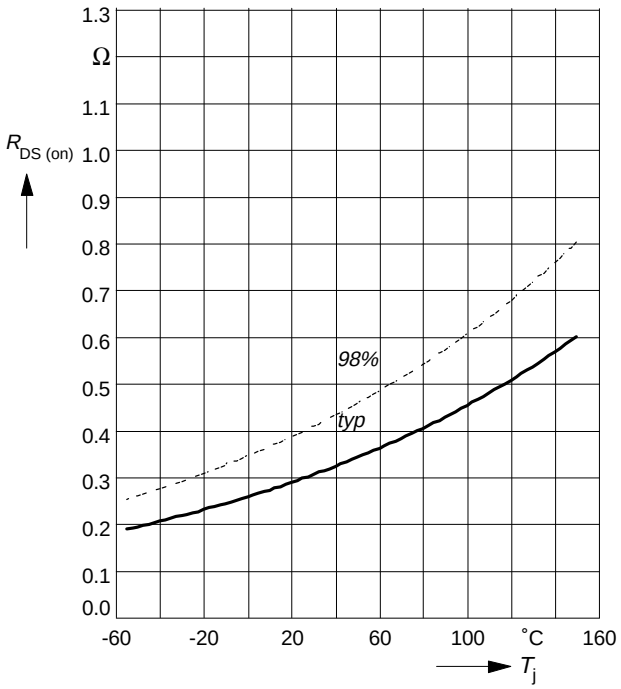
$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



**Drain-source on-resistance**

$R_{DS\ (on)} = f(T_j)$

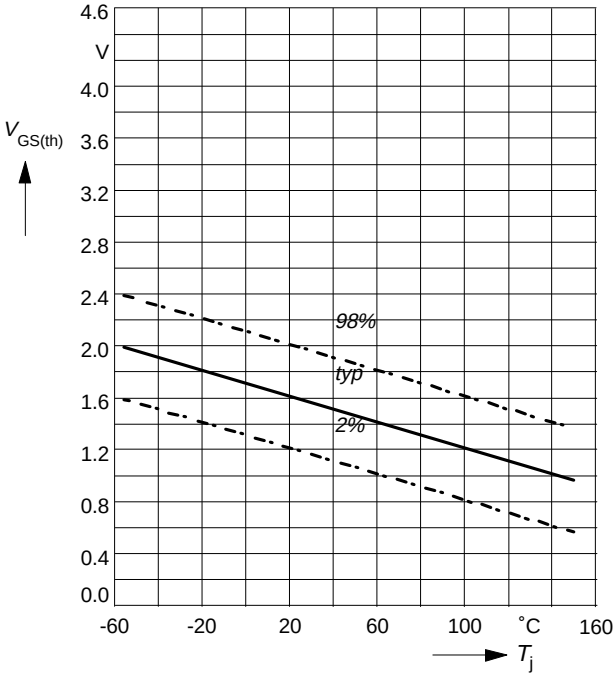
parameter: $I_D$ = 3.5 A, $V_{GS}$ = 5 V




**Gate threshold voltage**

$V_{GS\ (th)} = f(T_j)$

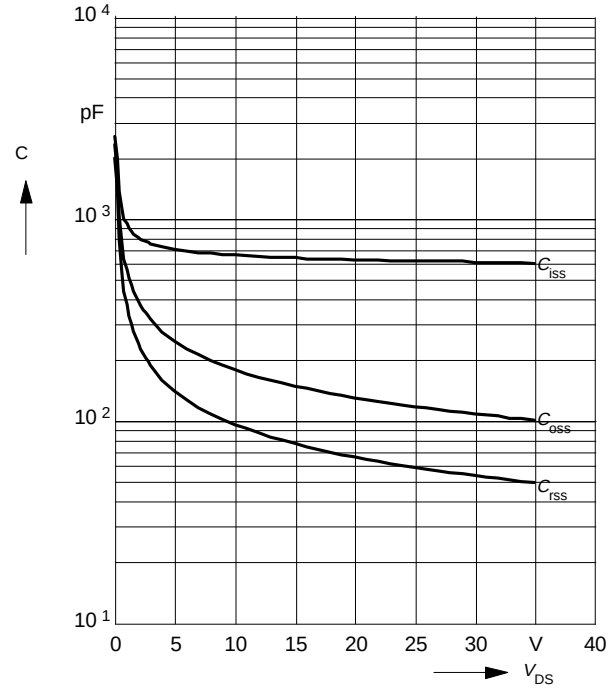
parameter: $V_{GS} = V_{DS}$, $I_D$ = 1 mA




**Typ. capacitances**

$C = f(V_{DS})$

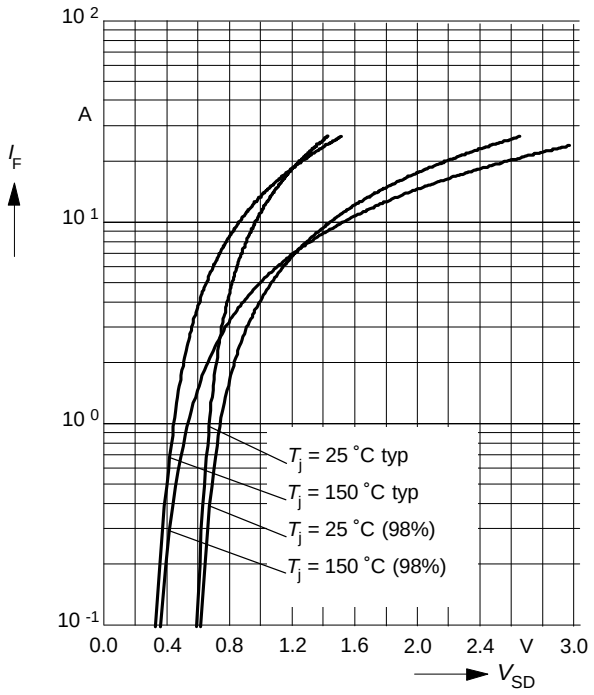
parameter: $V_{GS}$ = 0V, $f$ = 1MHz



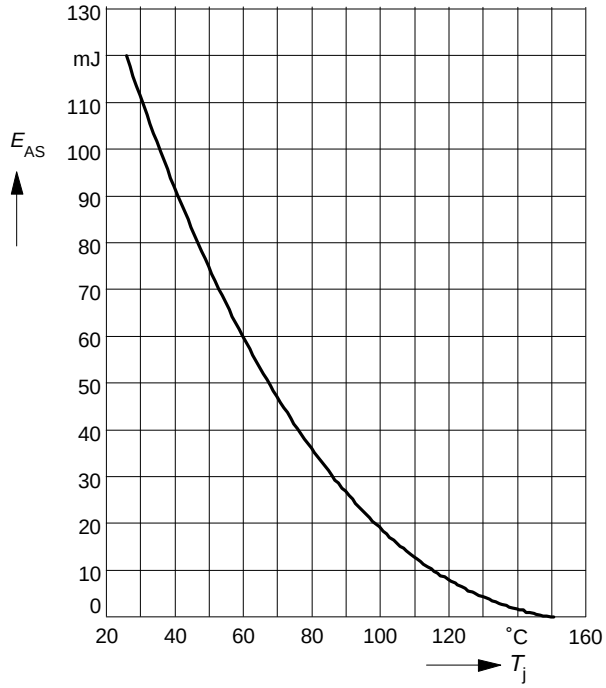

**Forward characteristics of reverse diode**

$I_F = f(V_{SD})$

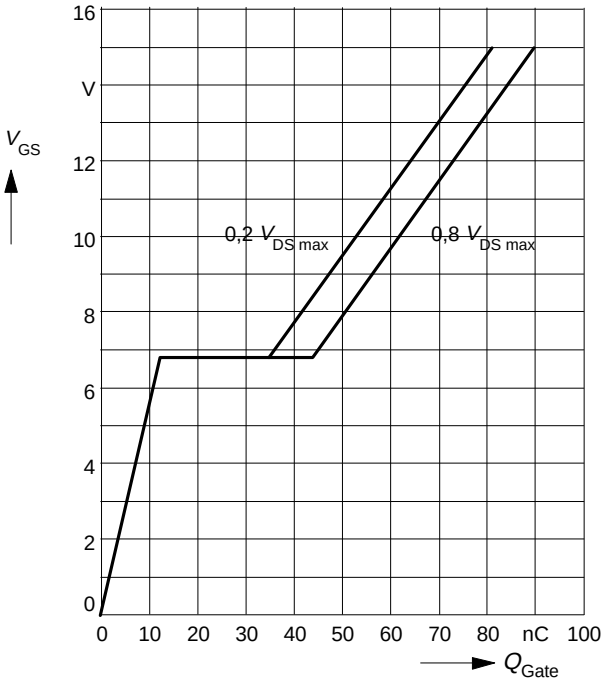
parameter: $T_j$, $t_p$ = 80 µs



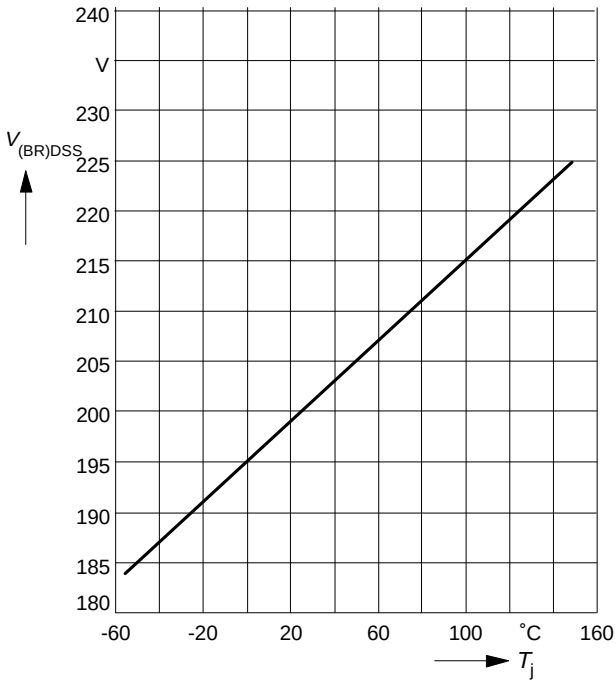
**Avalanche energy** $E_{AS} = f(T_j)$
parameter: $I_D$ = 7 A, $V_{DD}$ = 50 V
$R_{GS}$ = 25 Ω, $L$ = 3.67 mH



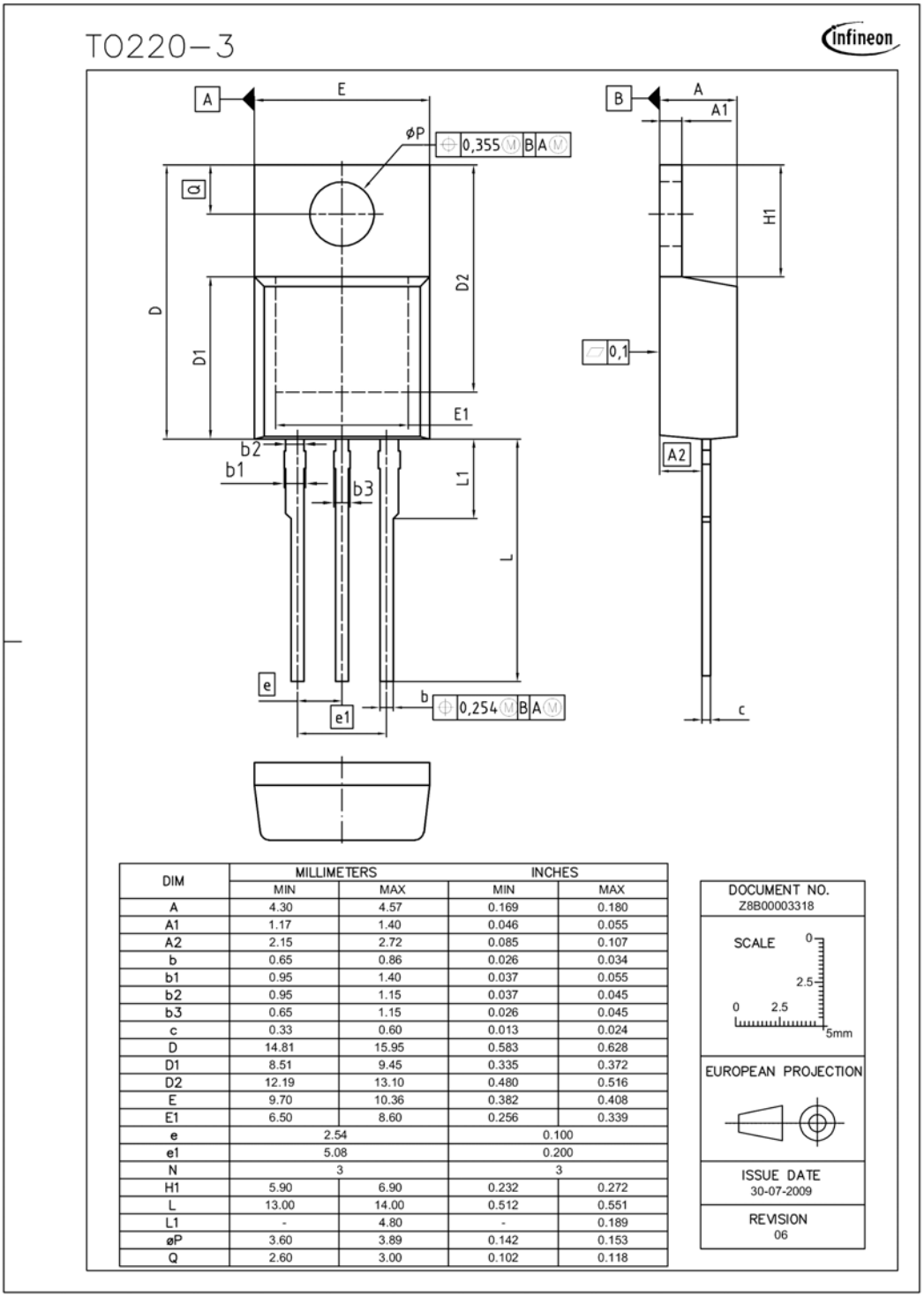

**Typ. gate charge**
$V_{GS} = f(Q_{Gate})$
parameter: $I_{D\ puls}$ = 63 A




**Drain-source breakdown voltage**
$V_{(BR)DSS} = f(T_j)$



## Package Drawing: TO220-3




| DIM | MILLIMETERS | | INCHES | |
|---|---|---|---|---|
| | MIN | MAX | MIN | MAX |
| A | 4.30 | 4.57 | 0.169 | 0.180 |
| A1 | 1.17 | 1.40 | 0.046 | 0.055 |
| A2 | 2.15 | 2.72 | 0.085 | 0.107 |
| b | 0.65 | 0.86 | 0.026 | 0.034 |
| b1 | 0.95 | 1.40 | 0.037 | 0.055 |
| b2 | 0.95 | 1.15 | 0.037 | 0.045 |
| b3 | 0.65 | 1.15 | 0.026 | 0.045 |
| c | 0.33 | 0.60 | 0.013 | 0.024 |
| D | 14.81 | 15.95 | 0.583 | 0.628 |
| D1 | 8.51 | 9.45 | 0.335 | 0.372 |
| D2 | 12.19 | 13.10 | 0.480 | 0.516 |
| E | 9.70 | 10.36 | 0.382 | 0.408 |
| E1 | 6.50 | 8.60 | 0.256 | 0.339 |
| e | 2.54 | | 0.100 | |
| e1 | 5.08 | | 0.200 | |
| N | 3 | | 3 | |
| H1 | 5.90 | 6.90 | 0.232 | 0.272 |
| L | 13.00 | 14.00 | 0.512 | 0.551 |
| L1 | - | 4.80 | - | 0.189 |
| øP | 3.60 | 3.89 | 0.142 | 0.153 |
| Q | 2.60 | 3.00 | 0.102 | 0.118 |

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